

Title (en)  
PHOTOCURABLE/THERMOSETTING COMPOSITION FOR FORMING MATTE FILM

Title (de)  
PHOTO- ODER WÄRMEHÄRTENDE ZUSAMMENSETZUNGEN ZUR HERSTELLUNG MATTER FILME

Title (fr)  
COMPOSITION PHOTODURCISSABLE/THERMODURCISSABLE PERMETTANT DE PRODUIRE UN FILM MAT

Publication  
**EP 1266922 A1 20021218 (EN)**

Application  
**EP 00902949 A 20000214**

Priority  
JP 0000795 W 20000214

Abstract (en)  
A photocurable and thermosetting composition which is useful in forming a matte film and can be developed with an aqueous alkaline solution is provided. The composition comprises (A) a photosensitive prepolymer obtained by causing a saturated or unsaturated polybasic acid anhydride to react with a hydroxyl group of an esterification product of a novolak type epoxy compound and an unsaturated monocarboxylic acid, (B) a carboxyl group-containing copolymer resin, (C) a photopolymerization initiator, (D) a diluent, (E) a polyfunctional epoxy compound having at least two epoxy groups in its molecule, and, when necessary, (F) an inorganic filler. The composition may further comprise (G) an epoxy resin curing agent. This composition can be advantageously used for the formation of a solder resist on a printed circuit board.

IPC 1-7  
**C08G 59/42**; **C08G 59/14**; **G03F 7/038**; **C09D 11/00**; **H05K 3/28**

IPC 8 full level  
**C08F 2/46** (2006.01); **C08G 59/14** (2006.01); **C08G 59/42** (2006.01); **C09D 4/00** (2006.01); **C09D 5/00** (2006.01); **C09D 11/00** (2006.01); **C09D 133/02** (2006.01); **C09D 157/10** (2006.01); **C09D 163/00** (2006.01); **G03F 7/027** (2006.01); **G03F 7/032** (2006.01); **G03F 7/038** (2006.01); **H05K 3/28** (2006.01)

CPC (source: EP KR US)  
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Citation (third parties)  
Third party :  
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• JP H1020493 A 19980123 - CIBA GEIGY JAPAN LTD  
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